XA-9665A
PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the application of:

Hiroshi AKASAKI et al.

Appln. No.:

Filed: HEREWITH

For: SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE

* * *

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Applicants wish to make of record the documents cited in prior Application No. 10/153,525 filed May 24, 2002, whether cited by Applicants or by the Patent Office. The documents are listed on the attached Form PTO-1449.

Respectfully submitted,

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April 14, 2004

| FORM PTO-1449<br><br>LIST OF DOCUMENTS CITED BY APPLICANT | Atty. Docket No.<br>XA-9665A | Appln. No. |
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| | Applicant<br>Hiroshi AKASAKI et al. | |
| | Filing Date<br>HEREWITH | Group |

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**OTHER** (including author, title, date, pertinent pages, etc.)

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| Examiner | Date Considered |
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